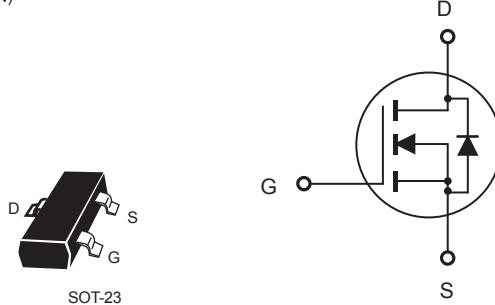


## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 20V, 3.6A,  $R_{DS(ON)} = 60m\Omega$  @ $V_{GS} = 4.5V$ .
- $R_{DS(ON)} = 70m\Omega$  @ $V_{GS} = 2.5V$ .
- $R_{DS(ON)} = 100m\Omega$  @ $V_{GS} = 1.8V$ .
- High dense cell design for extremely low  $R_{DS(ON)}$ .
- Lead free product is acquired.
- Rugged and reliable.
- SOT-23 package.



### ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Drain Current-Continuous	$I_D$	3.6	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	14	A
Maximum Power Dissipation	$P_D$	1.25	W
Operating and Store Temperature Range	$T_J, T_{Stg}$	-55 to 150	$^\circ C$

### Thermal Characteristics

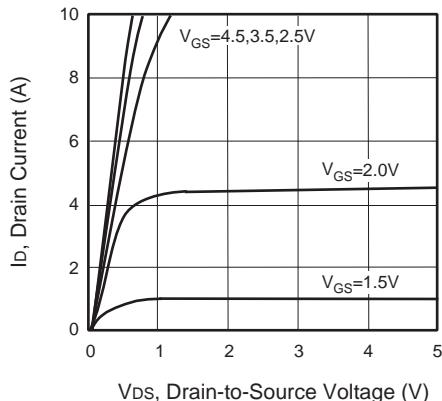
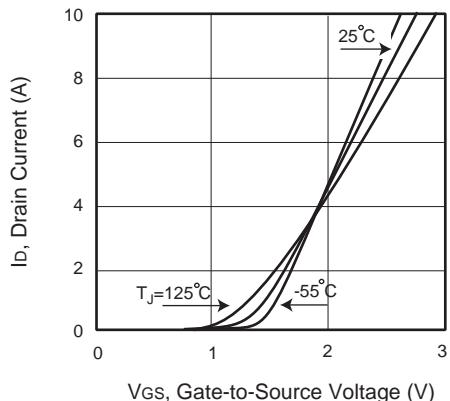
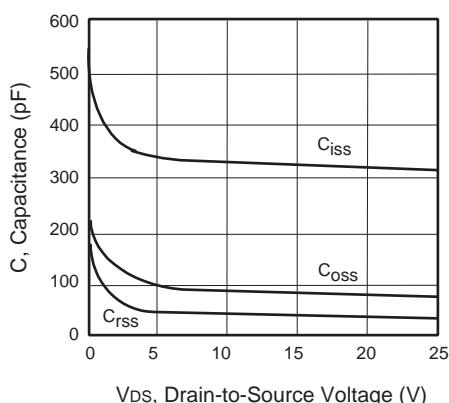
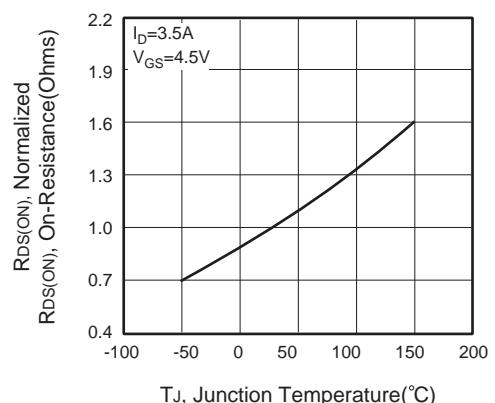
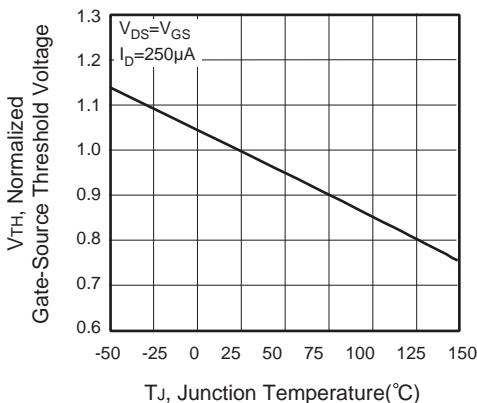
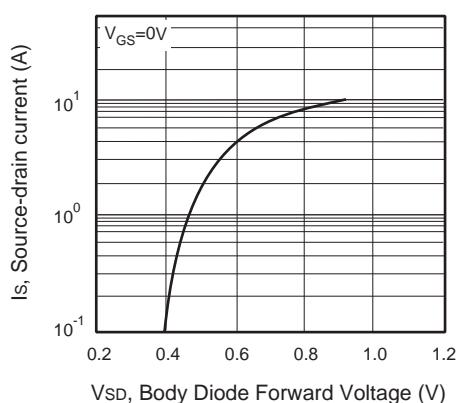
Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	100	$^\circ C/W$

**CES2306****Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 8\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -8\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics</b> <sup>c</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	0.4		1	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 3.6\text{A}$		43	60	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 3.1\text{A}$		55	70	$\text{m}\Omega$
		$V_{\text{GS}} = 1.8\text{V}, I_D = 1.0\text{A}$		70	100	$\text{m}\Omega$
<b>Dynamic Characteristics</b> <sup>d</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		330		pF
Output Capacitance	$C_{\text{oss}}$			90		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			60		pF
<b>Switching Characteristics</b> <sup>d</sup>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 10\text{V}, I_D = 3.6\text{A}, V_{\text{GS}} = 4.5\text{V}, R_{\text{GEN}} = 6\Omega$		8	16	ns
Turn-On Rise Time	$t_r$			7	14	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			30	60	ns
Turn-Off Fall Time	$t_f$			36	72	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 10\text{V}, I_D = 3.6\text{A}, V_{\text{GS}} = 4.5\text{V}$		5	6.5	nC
Gate-Source Charge	$Q_{\text{gs}}$			1		nC
Gate-Drain Charge	$Q_{\text{gd}}$			1		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				1	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 1\text{A}$			1.2	V

## Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.□
- b.Surface Mounted on FR4 Board,  $t \leq 10 \text{ sec.}$ □
- c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .□
- d.Guaranteed by design, not subject to production testing.□

**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

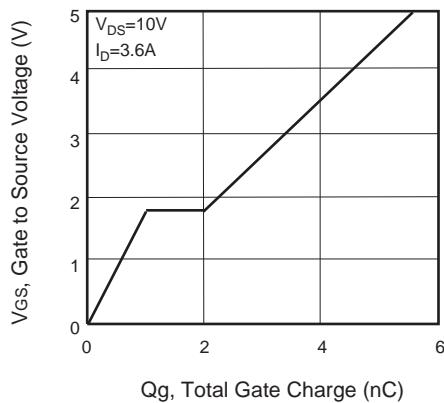


Figure 7. Gate Charge

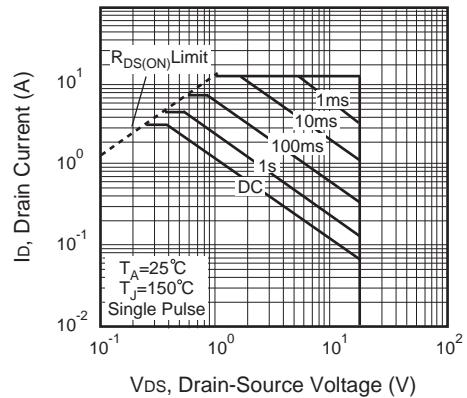


Figure 8. Maximum Safe Operating Area

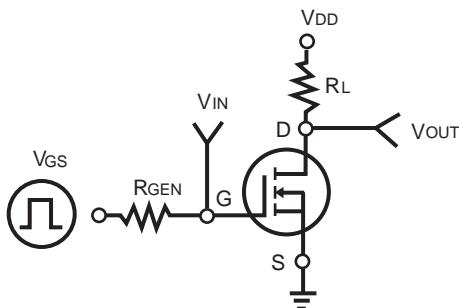


Figure 9. Switching Test Circuit

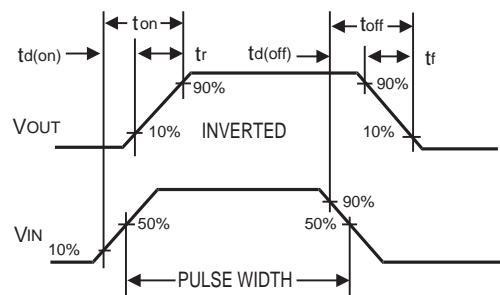


Figure 10. Switching Waveforms

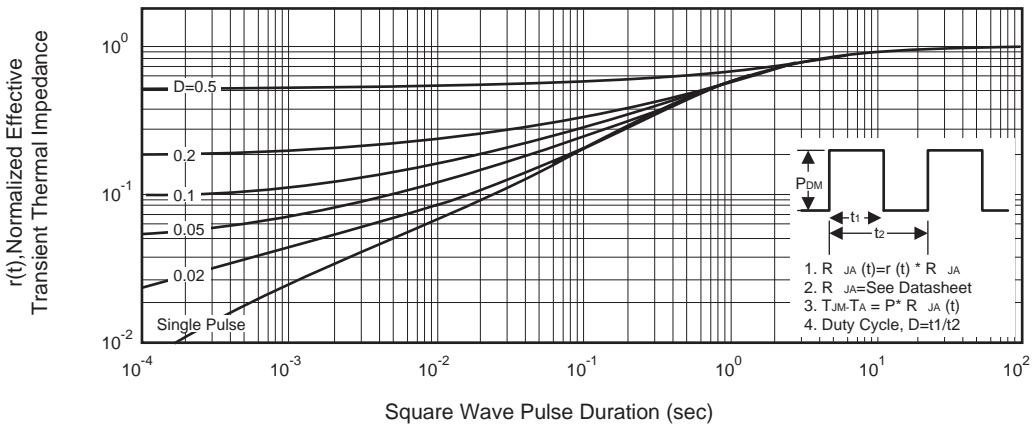


Figure 11. Normalized Thermal Transient Impedance Curve